MSKSEMI 美森科













ESD

TVS

TSS

MOV

GDT

PIFD

MMSD914

Product specification





FEATURES

High Voltage

Reference News

PACKAGE OUTLINE		MARKING	
	· · · · · · · · ·	5D	
SOD-123			

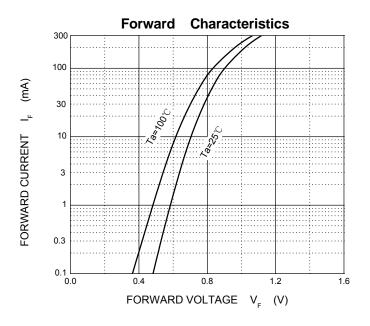
MAXIMUM RATINGS (Ta=25℃ unless otherwise noted)

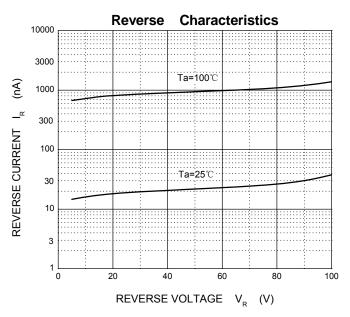
Symbol	Parameter	Value	Unit	
V _{RRM}	Maximum Repetitive Reverse Voltage	100	V	
lo	Forward Current	0.2	А	
IFSM	Non-repetitive Peak Forward Surge Current @t= 8.3ms	2		
P _D	Power Dissipation	400	mW	
R _{0JA}	Thermal Resistance from Junction to Ambient	312	°C/W	
T _j ,T _{stg}	Operation Junction and Storage Temperature Range	-55~+150	℃	

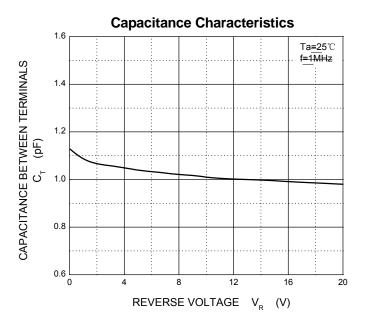
ELECTRICAL CHARACTERISTICS(Ta=25℃ unless otherwise specified)

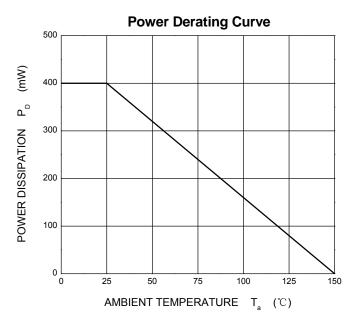
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Reverse voltage	$V_{(BR)}$	I _R =100µA	100			V
Reverse current	l R	V _R =20V			25	nA
		V _R =75V			5	μA
Forward voltage	VF	I⊧=10mA			1	V
Total capacitance	C _{tot}	V _R =0V,f=1MHz			4	pF
Reverse recovery time	t _{rr}	$I_F = I_R = 10$ mA, $I_{rr} = 0.1 \times I_R$, $R_L = 100\Omega$			4	ns





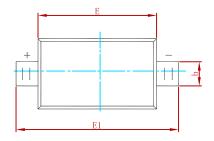


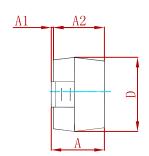


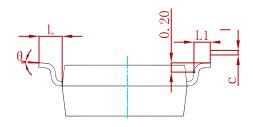




PACKAGE MECHANICAL DATA

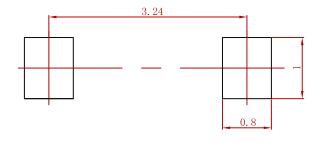






Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
Α	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.450	0.650	0.018	0.026
С	0.080	0.150	0.003	0.006
D	1.500	1.700	0.059	0.067
Е	2.600	2.800	0.102	0.110
E1	3.550	3.850	0.140	0.152
L	0.500 REF		0.020 REF	
L1	0.250	0.450	0.010	0.018
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

- 1.Controllng dlmenslon:in mlllmeters. 2.General tolerance:± 0.05mm.
- 3. The pad layout Is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MMSD914	SOD-123	3000



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